KL IR Series Photoresist

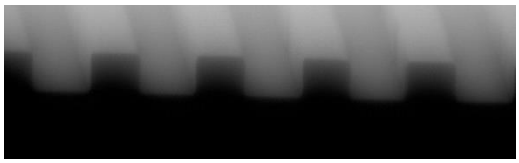
Image Reversible Resist

For i-Line, broadband and g-Line exposures

Negative Resist Mode Process Conditions	
Softbake	105 C for 90 seconds
Exposure	Broadband, i-line, g-line
Reversal Bake (critical step)	130 C for 90 seconds
Flood Exposure	150 mJ/cm2 (broadband)
Development	0.26N TMAH
Hardbake (optional)	130 C for 60 seconds
Removal	NMP / DMSO based strippers

Example 1: Negative tone Process

Film Thickness	1.5 microns
Broadband exposure	70 mJ/cm2
Develop time	60 seconds puddle (recommended)

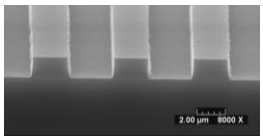


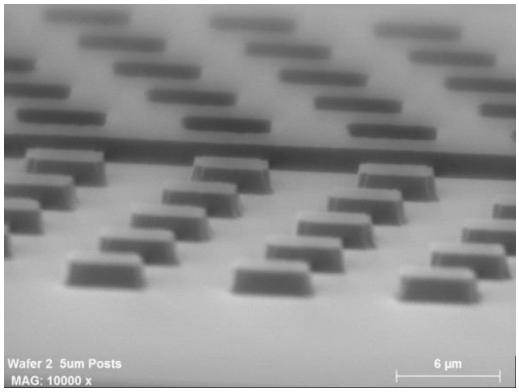
2 micron line/space

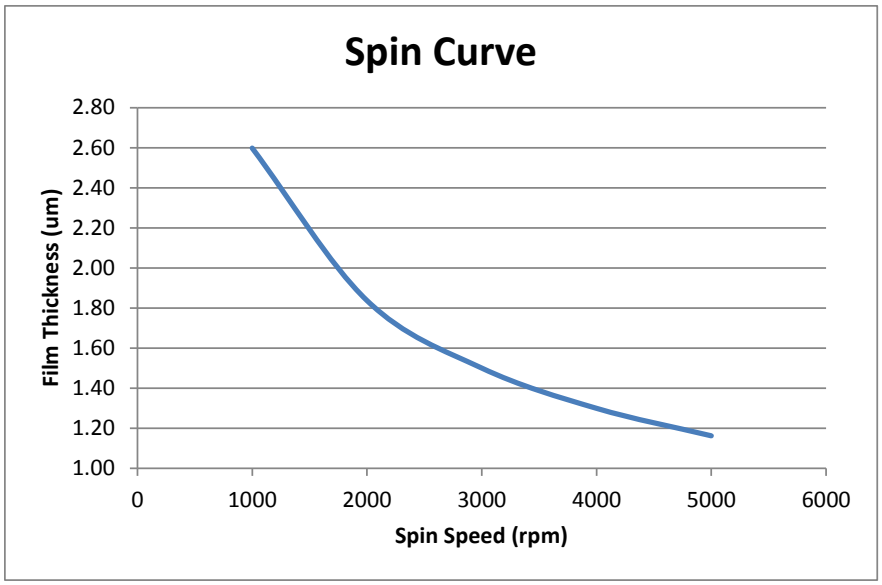
Positive Resist Mode Process Conditions	
Softbake	105 C for 90 seconds
Exposure	Broadband, i-line, g-line
PEB	115 C for 60 seconds
Development	0.26N TMAH develop
Removal	NMP or DMSO based strippers

Example 2: Positive tone Process

Film Thickness	1.5 microns
Broadband exposure	~70 mJ/cm2 at 1.5 um FT (broadband)
Develop time	60 seconds puddle (recommended)







Custom formulations available to adjust spin curve.

Handling & Disposal Considerations

Consult the MSDS for handling and appropriate PPE. KL IR contains a combustible liquid; keep away from ignition sources, heat, sparks and flames.

KL IR is compatible with typical waste streams used with photoresist processing. It is the user's responsibility to dispose in accordance with all local, state, and federal regulations.